

5.0mm x 5.0mm SURFACE MOUNT LED LAMP

Part Number: AAAF5051QR425Z3S-C1 Cool White



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Features

- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- White SMD package, silicone resin.
- Package: 500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

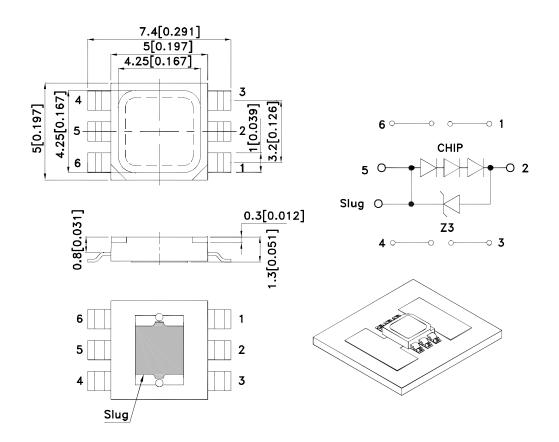
The source color devices are made with InGaN on Al₂O₃ substrate Light Emitting Diode.

Static electricity and surge damage the LEDs.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15[±0.006]unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

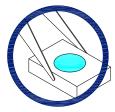


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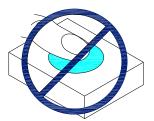
Handling Precautions

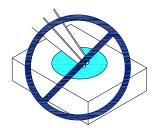
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

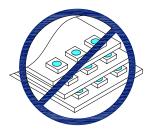


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

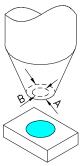




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

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Selection Guide

Part No.	Dice	Lens Type	lv (mo @ 15	,	Фv (lm) [2] @ 150mA		Viewing Angle [1]
			Min.	Тур.	Min.	Тур.	201/2
AAAF5051QR425Z3S-C1	Cool White (InGaN)	Water Clear	22000	37000	60	80	120°

- $1.\,\theta1/2$ is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity/ luminous Flux: +/-15%.
 Luminous intensity/ luminous Flux value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Value	Unit
Power dissipation	Po	1.575	W
Junction temperature[1]	TJ	140	°C
Reverse Voltage	VR	5	V
Operating Temperature	Тор	-40 To +85	°C
Storage Temperature	Tstg	-40 To +85	°C
DC Forward Current [1]	lF	150	mA
Peak Forward Current [2]	IFM	300	mA
Thermal resistance [1]	Rth j-a	90	°C/W
Electrostatic Discharge Threshold (HBM)	8000	V	

Notes:

Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Value	Unit	
Reverse Current (VR = 5V) [Max.]	lR	10	uA	
Color Temperature Ir=150mA [Min.]		5310		
Color Temperature IF=150mA [Typ.]	ССТ	6000	к	
Color Temperature IF=150mA [Max.]		7040		
Forward Voltage IF=150mA [Min.]		8.5		
Forward Voltage IF=150mA [Typ.]	VF [1]	9.5	V	
Forward Voltage Ir=150mA [Max.]		10.5		
Temperature coefficient of x IF=150mA, -10 $^{\circ}$ C \leq T \leq 100 $^{\circ}$ C [Typ.]	TCx	-2	10 ⁻³ /° C	
Temperature coefficient of y IF=150mA, -10 ° C≤ T≤100 ° C [Typ.]	ТСу	-1	10 ⁻³ /° C	
Temperature coefficient of VF IF=150mA, -10 ° C≤ T≤100 ° C [Typ.]	TCv	-2.3	mV/° C	

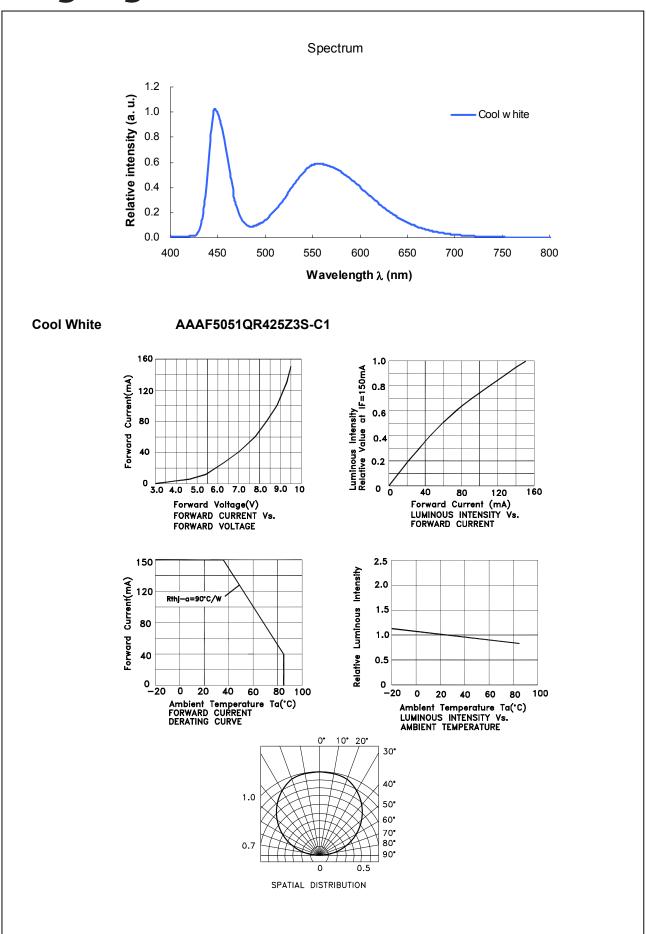
Note:

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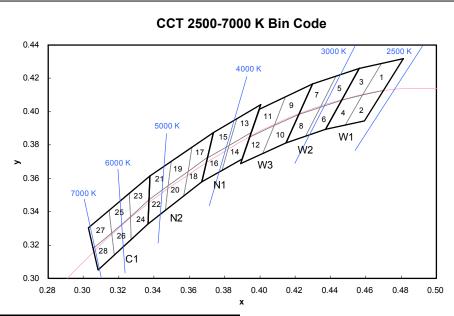
^{1.} Results from mounting on metal core PCB, mounted on pc board-metal core PCB is recommend.for lowest thermal resistance.

^{2. 1/10} Duty Cycle, 0.1ms Pulse Width.

^{1.} Forward Voltage: +/-0.1V.



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Group	Chromaticity Regions	CCT (K)				
Group	Chilomaticity Regions	Min.	Тур.	Max.		
W1	1, 2, 3, 4	2580	2700	2870		
W2	5, 6, 7, 8	2870	3000	3220		
W3	9, 10, 11, 12	3220	3500	3710		
N1	13, 14, 15, 16	3710	4000	4260		
N2	17, 18, 19, 20, 21, 22	4260	4700	5310		
C1	23, 24, 25, 26, 27, 28	5310	6000	7040		

Notes:

Shipment may contain more than one chromaticity regions. Orders for single chromaticity region are generally not accepted. Measurement tolerance of the chromaticity coordinates is ±0.01.

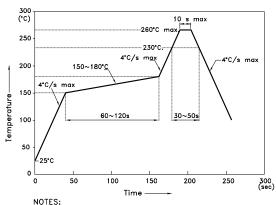
	20, 24, 20, 20, 21, 20 0010 0000 1040				l .						
	Х	у		Х	у		х	у		х	у
1	0.4582	0.4099	8	0.4147	0.3814		0.3702	0.3722		0.3481	0.3557
	0.4687	0.4289		0.4221	0.3984	15	0.3736	0.3874	22	0.3370	0.3472
'	0.4813 0.4319	0.4319		0.4342	0.4028	13	0.3869	0.3958		0.3364	0.3328
	0.4700	0.4126		0.4259	0.3853		0.3825	0.3798		0.3466	0.3411
	0.4483	0.3919		0.4080	0.3916		0.3670	0.3578		0.3376	0.3616
2	0.4582	0.4099	9	0.4146	0.4089	16	0.3702	0.3722	23	0.3260	0.3512
	0.4700	0.4126	١	0.4299	0.4165	10	0.3825	0.3798	23	0.3265	0.3371
	0.4593	0.3944		0.4221	0.3984		0.3783	0.3646		0.3370	0.3472
	0.4465	0.4071		0.4017	0.3751		0.3736	0.3874	24	0.3370	0.3472
3	0.4562	0.4260	10	0.4080	0.3916	17	0.3616	0.3788		0.3265	0.3371
	0.4687	0.4289	10	0.4221	0.3984	17	0.3592	0.3641	24	0.3270	0.3230
	0.4582	0.4099		0.4147	0.3814		0.3703	0.3726		0.3364	0.3328
	0.4373	0.3893		0.3941	0.3848		0.3703	0.3726		0.3260	0.3512
4	0.4465	0.4071	11	0.3996	0.4015	18	0.3592	0.3641	25	0.3144	0.3408
4	0.4582	0.4099		0.4146	0.4089	10	0.3568	0.3495	25	0.3160	0.3274
	0.4483	0.3919		0.4080	0.3916		0.3670	0.3578		0.3265	0.3371
	0.4342	0.4028		0.3889	0.3690		0.3616	0.3788		0.3265	0.3371
5	0.4430	0.4212	12	0.3941	0.3848	10	0.3496	0.3702	26	0.3160	0.3274
5	0.4562	0.4260	12	0.4080	0.3916	19	0.3481	0.3557		0.3175	0.3139
	0.4465	0.4071		0.4017	0.3751		0.3592	0.3641		0.3270	0.3230
	0.4259	0.3853		0.3825	0.3798		0.3592	0.3641		0.3144	0.3408
	0.4342	0.4028	40	0.3869	0.3958	20	0.3481	0.3557	07	0.3028	0.3304
6	0.4465	0.4071	13	0.4006	0.4044	20	0.3466	0.3411	27	0.3055	0.3177
	0.4373	0.3893		0.3950	0.3875		0.3568	0.3495		0.3160	0.3274
	0.4221	0.3984	4.4	0.3783	0.3646	21	0.3496	0.3702	20	0.3160	0.3274
	0.4299	0.4165		0.3825	0.3798		0.3376	0.3616		0.3055	0.3177
7	0.4430	0.4212	14	0.3950	0.3875		0.3370	0.3472	28	0.3081	0.3049
	0.4342	0.4028		0.3898	0.3716		0.3481	0.3557		0.3175	0.3139

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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



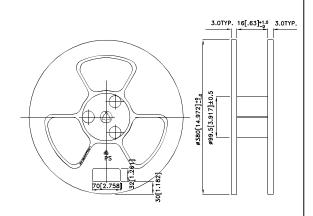
NOTES:

1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

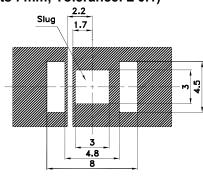
3.Number of reflow process shall be 2 times or less.

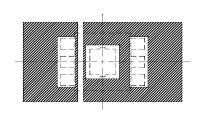
Reel Dimension



Recommended Soldering Pattern

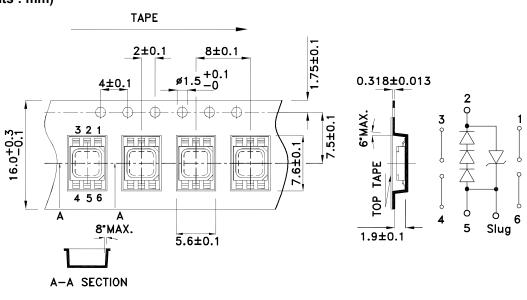
(Units: mm; Tolerance: ± 0.1)





Tape Specifications

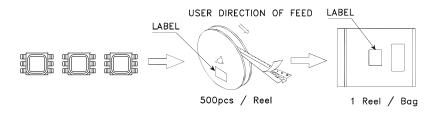
(Units: mm)

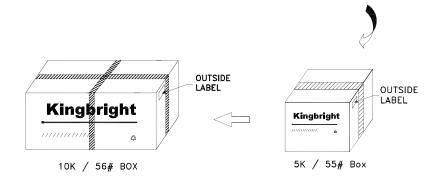


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PACKING & LABEL SPECIFICATIONS

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